



Material Content Data Sheet



Sales Product Name		TLE7278-2E V50		Issued		25. September 2017		
MA#		MA000970270						
Package		PG-SSOP-14-2		Weight*		83.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.362	2.83	2.83	28338	28338
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8267	
wire	non noble metal	copper	7440-50-8	27.978	33.57	34.45	335682	344465
	noble metal	gold	7440-57-5	0.171	0.20	0.20	2046	2046
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1176
encapsulation	plastics	epoxy resin	-	4.510	5.41		54118	
	inorganic material	silicondioxide	60676-86-0	44.418	53.30	58.83	532942	588236
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11712	11712
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9210	9210
glue	plastics	epoxy resin	-	0.333	0.40		3998	
	noble metal	silver	7440-22-4	1.000	1.20	1.60	11995	15993
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com